

ANNAMACHARYA INSTITUTE OF TECHNOLOGY & SCIENCES::KADAPA (AUTONOMOUS)

Utukur (Post), C.K. Dinne (V&M), Kadapa, YSR (Dist) Andhra Pradesh - 516 003 Approved by AICTE, New Delhi & Affiliated to JNTUA, Ananthapuramu Accredited by NAAC with 'A' Grade, Bangalore

Department of Electronics & Communication Engineering M.Tech. IN VLSI System Design

Effective for the batches admitted from 2023-24 *M.Tech –I Semester*

S.No	Category	Course Code	Course Title	Н	ours p week		Credits
				L	T	P	
1	PC	23VSDPC01	VLSI Technology	3	0	0	3
2	PC	23VSDPC02	CMOS Analog IC Design	3	0	0	3
3	PE	23VSDPE01a 23VSDPE01b 23VSDPE01c	Program Elective – I 1. Microchip Fabrication Techniques 2. Nano materials and Nanotechnology 3. CAD for VLSI	3	0	0	3
4	PE	23VSDPE02a 23VSDPE02b 23VSDPE02c	Program Elective – II 1. Device Modeling 2. FPGA Architectures and Applications 3. ASIC Design	3	0	0	3
5	MC	23VSDMC01	Research Methodology and IPR	2	0	0	2
6	PC	23VSDPC01L	VLSI Technology Lab	0	0	4	2
7	PC	23VSDPC02L	CMOS Analog IC Design Lab	0	0	4	2
8	AC	23VSDAC01a 23VSDAC01b 23VSDAC01c	Audit Course – I 1. English for Research paper writing 2. Disaster Management 3. Sanskrit for Technical Knowledge	2	0	0	0
			Total				18



ANNAMACHARYA INSTITUTE OF TECHNOLOGY & SCIENCES::KADAPA (AUTONOMOUS)

Utukur (Post), C.K. Dinne (V&M), Kadapa, YSR (Dist) Andhra Pradesh - 516 003 Approved by AICTE, New Delhi & Affiliated to JNTUA, Ananthapuramu Accredited by NAAC with 'A' Grade, Bangalore

Department of Electronics & Communication Engineering M.Tech. IN VLSI System Design

Effective for the batches admitted from 2023-24

M.Tech –II Semester

S.No	Category	Course Code	Course Title	Н	ours p week		Credits
			200000	L	T	P	
1	PC	23VSDPC03	CMOS Mixed Signal IC Design	3	0	0	3
2	PC	23VSDPC04	CMOS Digital IC Design	3	0	0	3
3	PE	23VSDPE03a 23VSDPE03b 23VSDPE03c	Program Elective – III 1. Physical Design Automation 2. Semiconductor Memory Design and Testing 3. Testing & Testability	3	0	0	3
4	PE	23VSDPE04a 23VSDPE04b 23VSDPE04c	Program Elective – IV 1. Low Power VLSI Design 2. IoT and its Applications 3. VLSI Signal Processing	3	0	0	3
5	PR	23VSDPR01	Technical seminar	0	0	4	2
6	PC	23VSDPC03L	CMOS Digital IC Design Lab	0	0	4	2
7	PC	23VSDPC04L	CMOS Mixed Signal Lab	0	0	4	2
8	AC	23VSDAC02a 23VSDAC02b 23VSDAC02c	Audit Course – II 1.Pedagogy Studies 2.Stress Management for Yoga 3.Personality Development through Life Enlightenment Skills	2	0	0	0
			Total				18

Course Code	VI CLEECHNOLOGY	L	T	P	С
23VSDPC01	VLSI TECHNOLOGY	3	0	0	3
	Semester				

- 1. To give exposure to different steps involved in fabrication of ICs using MOS transistor, CMOS/BICOM transistors and passive components.
- 2. To provide knowledge on electrical properties of MOS &BICMOS devices to analyze the Behavior of inverters designed with various loads.
- 3. To provide concepts to design building blocks of data path of any system using gates.
- 4. To teach about basic programmable logic devices and testing of CMOS circuits.

Course Outcomes (CO): Student will be able to

- 1. Acquire qualitative knowledge about the fabrication process of integrated circuit using MOS transistors,
- 2. Draw the layout of any logic circuit which helps to understand and estimate parasitic of any logic circuit
- 3. Design building blocks of data path using gates.
- 4. Design simple memories using MOS transistors and can understand design of large memories
- 5. Understand the concept of testing and adding extra hardware to improve testability of system

UNIT - I Lecture Hrs: 9

REVIEW OF MICROELECTRONICS AND INTRODUCTION TO MOS

TECHNOLOGIES: (MOS, CMOS, Bi-CMOS) Technology Trends And Projections. Basic Electrical Properties OF MOS, CMOS & BICOMS CIRCUITS: Ids-Vds Relationships, Threshold Voltage Vt, Gm, Gds And Wo, Pass Transistor, MOS, CMOS & Bi- CMOS Inverters, Zpu/Zpd, MOS Transistor Circuit Model, Latch-Up In CMOS Circuits.

UNIT - II Lecture Hrs: 9

LAYOUT DESIGN AND TOOLS: Transistor Structures, Wires and Vias, Scalable

Design Rules, Layout Design Tools. LOGIC GATES & LAYOUTS: Static Complementary Gates, Switch Logic, Alternative Gate Circuits, Low Power Gates, Resistive and Inductive Interconnect Delays.

UNIT - III Lecture Hrs: 8

COMBINATIONAL LOGIC NETWORKS: Layouts, Simulation, Network delay, Interconnect Design, Power Optimization, Switch Logic Networks, Gate and Network Testing. SEQUENTIAL SYSTEMS: Memory Cells and Arrays, Clocking Disciplines, Design, Power Optimization, Design Validation and Testing.

UNIT - IV Lecture Hrs: 9

FLOOR PLANNING & ARCHITECTURE DESIGN: Floor Planning Methods, Off-Chip Connections, High Level Synthesis, Architecture for Low Power, SOCs and Embedded CPUs, Architecture Testing.

UNIT - V Lecture Hrs: 8

INTRODUCTION TO CAD SYSTEMS (ALGORITHMS) AND CHIP DESIGN: Layout Synthesis and Analysis, Scheduling and Printing; Hardware-Software Co-design, Chip Design Methodologies- A simple Design Example.

Textbooks:

- 1. Essentials of VLSI Circuits and Systems, K. Eshraghian, EshraghianDougles, A. Pucknell, PHI of India Ltd.,2005.
- 2. Modern VLSI Design, 3rd Edition, Wayne Wolf, Pearson Education, fifth Indian Reprint, 2005.

- 1. Principals of CMOS Design N.H.E Weste, K.Eshraghian, Adison Wesley, 2nd Edition.
- 2. Introduction to VLSI Design Fabricius, MGH International Edition, 1990.
- 3. CMOS Circuit Design, Layout and Simulation Baker, Li Boyce, PHI, 2004.

Course Code	CMOS ANALOG IC DESIGN	L								
23VSDPC02	CINOS ANALOGIC DESIGN	3	0	0	3					
	Semester		I							
Course Objecti	ves:									
1. This cou	urse focuses on theory, analysis and design of analog integrated circles (MOS) technologies.	cuits in	both I	Bipolai	r and					
	esign concepts, issues and tradeoffs involved in analog IC design are	explor	ed.							
	e understanding and real-life applications are emphasized throughout									
	n about Design of CMOS Op Amps, Compensation of Op Amps, I			o-Stag	e Op					
Amps, 1	Power Supply Rejection Ratio of Two-Stage Op Amps, Cascade (jues of OP Amp.									
	w about Characterization of Comparator, Two-Stage, Open-Loop	Compa	rators	Impro	vino					
	formance of Open-Loop Comparators, Discrete-Time Comparators et		autors,	mpre	/ · · · · · · ·					
	nes (CO): Student will be able to									
	MOSFET based analog integrated circuits.									
_	e analog circuits at least to the first order.									
	ate the trade-offs involved in analog integrated circuit design.									
	and and appreciate the importance of noise and distortion in analog of	rircuits								
	e complex engineering problems critically in the domain of analog I			condu	cting					
research		e desi	B11 101	Conaa	oum ₈					
	ngineering problems for feasible and optimal solutions in the core are	ea								
UNIT - I			cture H							
Basic MOS De	vice Physics: General Considerations, MOS I/V Characteristics, Sec	ond O	rder eft	fects, I	MOS					
Device models	and MOS Capacitor. Short Channel Effects and Device Models. Si	ngle S	tage A	mplifi	ers –					
	Common Source Stage, Source Follower, Common Gate Stage, Cas	code S	tage.							
UNIT - II		Le	cture F	Irs:						
Differential An	nplifiers: Single Ended and Differential Operation, Basic Different	ial Pai	r, Com	mon N	M ode					
Response, Diffe	erential Pair with MOS loads, Gilbert Cell. Passive and Active C	Current	Mirro	rs – l	Basic					
Current Mirrors	, Cascode Current Mirrors, Active Current Mirrors. Current Steering	Circui	t							
UNIT - III		I	Lecture	Hrs:						
	sponse of Amplifiers: General Considerations, Common Source S									
Common Gate S	Stage, Cascode Stage, Differential Pair. Noise – Types of Noise, Re	presen	tation	of Noi	se in					
circuits, Noise in	n single stage amplifiers, Noise in Differential Pairs.									
UNIT - IV		I	Lecture	Hrs:						
Feedback Am	plifiers: General Considerations, Feedback Topologies, Effect of	f Loa	ding. (Operat	ional					
Amplifiers – Ge	eneral Considerations, One Stage Op Amps, Two Stage Op Amps, Ga	ain Boo	osting,	Comm	non –					
	, Input Range limitations, Slew Rate, Power Supply Rejection, Nois									
and Frequency (Compensation.									
UNIT - V		I	Lecture	Hrs:						
Comparators:	Characterization of comparator, Two-Stage, Open-Loop compara	ators,	Other (Open-l	Loop					
-	nproving the Performance of Open-Loop Comparators, Discrete-Tim	-			•					
Textbooks:										
	esign of Analog CMOS Integrated Circuits", 2ndEdition, McGraw Hi	ll Editi	ion201	5.						
	Robert G. Meyer, "Analysis and Design of Analog Integrated Circu									
5thEdition, 2009										
Reference Bool	ze•									

- 1.T.C.Carusone, D.A.Johns&K.Martin, "Analog Integrated Circuit Design", 2ndEdition, Wiley, 2012.
- 2. P.E.Allen&D.R.Holberg, "CMOS Analog Circuit Design", 3rd Edition, Oxford University Press, 2011. 3. R.Jacob Baker, "CMOS Circuit Design, Layout, and Simulation", 3rdEdition, Wiley, 2010.
- 4. Adel S. Sedra, Kenneth C. Smith, Arun, "Microelectronic Circuits", 6th Edition, Oxford University Press

Course Code	MICROCHIP FABRICATION TECHNIQUES	L	T	P	С
23VSDPE01a	Program Elective – I	3	3		
	Semester		I		
Course Objectiv					
1. Compreh	end impact of semiconductor industry on the design of developmen	t of int	egrated	circu	its.
	with clean room technology				
	nd oxidation methods, aspects of photolithography, diffusion, ion ir				ies.
2	NMOS and CMOS design rules corresponding to 180nm, 90nm and	45nm	technol	ogies	
	nd packaging principles				
	es (CO): Student will be able to				
	and various stages of fabrication				
	nd Various packaging techniques and Design rules.				
	various thin films and its characteristics.				
UNIT - I			cture H		
	Processing: Overview of semiconductor industry, Stages of Mar		_		
	Crystal growth, Basic wafer fabrication operations, process yields,	Semice	onducto	or mat	erial
	d measurement, Contamination sources, Clean room construction.				
UNIT - II		Le	cture H	rs:	
	y:Oxidation and Photolithography, Ten step patterning process				
	toresists, Storage and control of photoresists, photo masking proc	ess, Ha	ard bak	e, dev	elop
	ing Wet etching, resist stripping.				
UNIT - III			ecture		
	Implantation: Doping and depositions: Diffusion process ste	ps, dep	osition	, Driv	ve-in
	plantation-1, Ion implantation-2.				
UNIT - IV		L	ecture	Hrs:	
	s and Growth: Metallization, CVD basics, CVD process step		w press	sure (CVD
	enhanced CVD systems, Vapour phase epitaxy, molecular beam epi				
UNIT - V		I	ecture	Hrs:	
Yield: Design r	ales and Scaling, BICMOS ICs: Choice of transistor types, PN	P trans	sistors,	Resis	stors,
capacitors.					
0 0	characteristics, package functions, package operations.				
Textbooks:					
	, Microchip fabrication, McGraw Hill, 1997.				
	., Deal, M.D. and Griffin, P.B., "Silicon VLSI Technology: Fun	damen	als, Pr	actice	and
	d., Prentice-Hall, 2000.				
Reference Books					
	d S.M. Sze, ULSI technology, McGraw Hill, 2000				
	LSI Fabrication principles, John Wiley and Sons, NY, 1994				
3. S.M. Sze, VLS	I technology, McGraw-Hill Book company, NY, 1988				

	NAME OF THE PARTY	т	T	D			
Course Code	NANOMATERIALS AND NANOTECHNOLOGY	L	T	P	C		
23VSDPE01b	Program Elective – I	3	0	0	3		
	Semester	I					
Course Objective							
	stand the basic idea behind the design and fabrication of nano		•				
2. To under future app	stand and frmulate new engineering solutions for current problem	ms and	techno	ologie	s for		
	re knowledge on the operation of fabrication and characteriza	tion de	wiees 1	o ook	iovo		
_	designed systems.	tion uc	vices i	o aci	neve		
	s (CO): Student will be able to						
	nd the basic science behind the design and fabrication of nano	o scale	cycter	ne			
	and and formulate new engineering solutions for current pro-		•		etina		
	ies for future applications.	ooiciiis	and	comp	Jung		
	er disciplinary projects applicable to wide areas by clearing and	fixing	the bou	ındari	es in		
	evelopment.						
•	tailed knowledge of the operation of fabrication and characterize	ation d	evices	to ach	nieve		
	designed systems.						
UNIT - I	•	Le	cture H	rs:			
Introduction of n	ano materials and nanotechnologies, Features of nanostructures	s, App	lication	s of	nano		
materials and tech	nnologies. Nano dimensional Materials 0D, 1D, 2D structures – S	ize Êff	ects - I	Fractio	on of		
Surface Atoms –	Specific Surface Energy and Surface Stress - Effect on the Latt	ice Par	ameter	- Ph	onon		
	- the General Methods available for the Synthesis of Nanost						
	ermal/solvo thermal methods – suitability of such methods for scali				,		
UNIT - II			cture H				
Fundamentals o	f nonmaterial's, Classification, Zero-dimensional nonmate	rials,	One-di	mens	ional		
	vo-dimensional nano materials, three dimensional nonmateri						
	d its Applications, Synthesis, Properties and applications of Lo	w Dim	ensiona	ıl Car	bon-		
Related Nanomate	erials.						
UNIT - III			ecture				
	ithography Techniques, Emerging Applications, Introduction to M						
	S), Advantages and Challenges of MEMS, Fabrication	Techn	ologies	, Su	rface		
	Bulk Micromachining, Molding. Introduction to Nano Phonics.						
UNIT - IV		I	ecture	Hrs:			
T . 1		\sim			c		

Introduction, Synthesis of CNTs - Arc-discharge, Laser-ablation, Catalytic growth, Growth mechanisms of CNT"s - Multi-walled nanotubes, Single-walled nano tubes Optical properties of CNT"s, Electrical transport in perfect nanotubes, Applications as case studies. Synthesis and Applications of CNTs.

UNIT - V Lecture Hrs:

Ferroelectric materials, coating, molecular electronics and Nano electronics, biological and environmental, membrane based application, polymer based application.

Textbooks:

- 1. Kenneth J.Klabunde and Ryan M.Richards, "Nanoscale Materials in Chemistry", 2ndedition, John Wiley and Sons, 2009.
- 2. I Gusev and A Rempel, "Nanocrystalline Materials", Cambridge International Science Publishing, 1stIndian edition by Viva Books Pvt. Ltd. 2008.
- 3. B.S.Murty, P.Shankar, Baldev Raj, B.B.Rath, James Murday, "Nanoscience and Nanotechnology", Tata McGrawHill Education 2012.

- Digital Integrated Circuit Design Ken Martin, Oxford University Press, 2011.
 Digital Integrated Circuits A Design Perspective, Jan M.Rabaey, AnantChandrakasan, Borvivoje Nikolic, 2nd Edition, PHI.

Course Code	CAD FOR VLSI	L	T	P	С
23VSDPE01c	Program Elective – I	3	0	0	3
	Semester				

- 1. To understand the various phases of CAD for digital electronic systems, from digital logic simulation to physical design, including test and verification.
- 2. To demonstrate knowledge and understanding of fundamental concepts in CAD and to establish capability for CAD tool development and enhancement.
- 3. To practice the application of fundamentals of VLSI technologies
- 4. To optimize the implemented design for area, timing and power by applying suitable constraints.

Course Outcomes (CO): Student will be able to

- 1. Establish comprehensive understanding of the various phases of CAD for digital electronic systems, from digital logic simulation to physical design, including test and verification.
- 2. Demonstrate knowledge and understanding of fundamental concepts in CAD and to establish capability for CAD tool development and enhancement.
- 3. Practice the application of fundamentals of VLSI technologies
- 4. Optimize the implemented design for area, timing and power by applying suitable constraints.

UNIT - I Lecture Hrs:

Introduction: VLSI Design Cycle, New Trends in VLSI Design Cycle, Physical Design Cycle, New Trends in Physical Design Cycle, Design Styles, System Packaging Styles.

UNIT - II Lecture Hrs:

Partitioning: Partitioning, Pin Assignment and Placement: Partitioning – Problem formulation, Classification of Partitioning algorithms, Kernighan-Lin Algorithm, Simulated Annealing.

UNIT - III Lecture Hrs:

Floor Planning :Floor Planning – Problem formulation, Classification of floor planning algorithms, constraint based floor planning, Rectangular Dualization, Pin Assignment – Problem formulation, Classification of pin assignment algorithms, General and channel Pin assignments.

UNIT - IV Lecture Hrs:

Placement and Routing: Placement–Problem formulation, Classification of placement algorithms, Partitioning based placement algorithms.

Global Routing and Detailed Routing: Global Routing – Problem formulation, Classification of global routing algorithms, Maze routing algorithms, Detailed Routing – Problem formulation, Classification of routing algorithms, Single layer routing algorithms.

UNIT - V Lecture Hrs:

Physical Design Automation of FPGAs and MCMs: FPGA Technologies, Physical Design cycle for FPGAs, Partitioning, Routing – Routing Algorithm for the Non-Segmented model, Routing Algorithms for the Segmented Model; Introduction to MCM Technologies, MCM Physical Design Cycle.

Textbooks:

- 1. Algorithms for VLSI Physical Design Automation by Naveed Shervani, 3rd Edition, 2005, Springer International Edition.
- 2. CMOS Digital Integrated Circuits Analysis and Design Sung-Mo Kang, Yusuf Leblebici, TMH, 3rd Ed., 2011.

- 1. VLSI Physical Design Automation-Theory and Practice by Sadiq M Sait, Habib Youssef, World Scientific.
- 2. Algorithms for VLSI Design Automation, S. H. Gerez, 1999, Wiley student Edition, John Wiley and Sons (Asia) Pvt. Ltd.
- 3. VLSI Physical Design Automation by Sung Kyu Lim, Springer International Edition.

Course Code	DEVICE MODELLING	L	T	P	C			
23VSDPE02a	Program Elective – II	3	0	0	3			
	Semester		I					
Course Objectiv								
1. To understand the physics of 2-terminal MOS operation and its characteristics								
	llyze the SOI MOSFET electrical characteristics.							
	es (CO): Student will be able to							
	1. Understand the physics of 2-terminal MOS operation and its characteristics							
	nd the physics of 4-terminal MOSFET operation and its characteris	tics.						
3. Analyze the SOI MOSFET electrical characteristics.								
UNIT - I			cture H					
	device: threshold voltage modelling (ideal case as well as consideration)	dering	the effe	ects of	f Qf,			
Φms and Dit.).								
UNIT - II		Lecture Hrs:						
	cs (ideal case as well as taking into account the effects of Qf, Φ ms				citor			
	ol (measurement of non-uniform doping profile, estimation of Qf,							
UNIT - III			cture H					
	FET: threshold voltage (considering the substrate bias); above t	hresho	ld I-V	mode	lling			
(SPICE level 1,2,	3 and 4).							
UNIT - IV			cture H					
	rrent model; scaling; effect of threshold tailoring implant (analytical							
	a approximation); buried channel MOSFET. Short channel, DIBL a	nd nari	ow wie	lth eff	ects;			
	ysis of MOSFETs (Meyer's model)							
UNIT - V			cture H					
	Basic structure; threshold voltage modelling Advanced topics:	hot car	rriers i	n cha	nnel;			
	s; high-K gate dielectrics.							
Textbooks:								
	sics of Semiconductor Devices, (2e), Wiley Eastern, 1981.	D. I.	1.0017					
	Fundamentals of Nanotransistors, World Scientific Publishing Co	Pte Lto	1 201 / .					
Reference Books		.07						
1	Operation and Modelling of the MOS Transistor, McGraw-Hill, 19	8/.						
	r-carrier Effects in MOS Trasistors, Academic Press, 1995.							
3. J. P. Colinge, "F	inFETs and Other Multi-Gate Transistors," Springer. 2009							

Course Code	FPGA ARCHITECTURES AND APPLICATIONS	I.	Т	Р	С	
23VSDPE02b	Program Elective – II	3	0	0	3	
Semester I						
Course Objectiv	Course Objectives:					
 To acqu 	ire knowledge about various architectures and device technologies.	ogies o	f PLD	's.		
2. To comp	2. To comprehend FPGA Architectures.					
3. To analyze System level Design and their application for Combinational and Sequential Circuits.						

4. To familiarize with Anti-Fuse Programmed FPGAs. To apply knowledge of this subject for various decided.

5. To apply knowledge of this subject for various design applications.

Course Outcomes (CO): Student will be able to

- 1. Acquire knowledge about various architectures and device technologies of PLD's.
- 2. Comprehend FPGA Architectures.
- 3. Analyze System level Design and their application for Combinational and Sequential Circuits.
- 4. Familiarize with Anti-Fuse Programmed FPGAs.
- 5. Apply knowledge of this subject for various design applications.

UNIT - I Lecture Hrs: **Introduction to Programmable Logic Devices:** Introduction, Simple Programmable Logic Devices – Read Only Memories, Programmable Logic Arrays, Programmable Array Logic, Programmable Logic Devices/Generic Array Logic; Complex Programmable Logic Devices-Architecture of Xilinx Cool Runner XCR3064XL CPLD, CPLD Implementation of a Parallel Adder with Accumulation. UNIT - II Lecture Hrs: Field Programmable Gate Arrays:Organization of FPGAs, FPGA Programming Technologies, Programmable Logic Block Architectures, Programmable Interconnects, and Programmable I/O blocks in FPGAs, Dedicated Specialized Components of FPGAs, and Applications of FPGAs. UNIT - III Lecture Hrs: SRAM Programmable FPGAs:Introduction, Programming Technology, Device Architecture, the Xilinx XC2000, XC3000 and XC4000 Architectures. UNIT - IV Lecture Hrs: Anti-Fuse Programmed FPGAs:Introduction, Programming Technology, Device Architecture, The Actel ACT1, ACT2 and ACT3 Architectures. UNIT - V Lecture Hrs: Design Applications: General Design Issues, Counter Examples, A Fast Video Controller, A Position

Design Applications: General Design Issues, Counter Examples, A Fast Video Controller, A Position Tracker for a Robot Manipulator, A Fast DMA Controller, Designing Counters with ACT devices, Designing Adders and Accumulators with the ACT Architecture.

Textbooks:

- 1. Field Programmable Gate Array Technology Stephen M. Trimberger, Springer International Edition.
- 2. Digital Systems Design Charles H. Roth Jr, LizyKurian John, Cengage Learning.

- 1. Field Programmable Gate Arrays-John V.Oldfield, Richard C.Dorf, Wiley India.
- 2. Digital Design Using Field Programmable Gate Arrays Pak K. Chan/SamihaMourad, Pearson Low Price Edition.
- 3. Digital Systems Design with FPGAs and CPLDs-Ian Grout, Elsevier, Newnes.
- 4. FPGA based System Design-Wayne Wolf, Prentice Hall Modern Semiconductor Design Series.

Course Code	ASIC DESIGN	L	T	P	C	
23VSDPE02d	Program Elective – II	3	0	0	3	
	Semester		I			
Course Object	ives:					
1. To und	derstand different types of ASICs and their libraries.					
2. To und	erstand about programmable ASICs, I/O modules and their inter conr	nects.				
3. To fam	niliarize different methods of software ASIC design their simulation,	testing	and co	onstru	ction	
of ASI						
	mes (CO): Student will be able to					
	different types of ASICs and their libraries.					
	about programmable ASICs, I/O modules and their inter connects.					
	lifferent methods of software ASIC design their simulation, testing an	d cons	truction	ı of		
ASICs.						
UNIT - I		Lecture Hrs:				
	to ASICs: Types of ASICs, Design Flow, Case Study, Economic					
	sistors as resistors, Transistor Parasitic Capacitance, Logical Effo		rary Ce	ell De	sign,	
•	ecture, Gate-Array Design, Standard Cell Design, Data Path Cell Design					
UNIT - II			cture H			
	e ASICs and Programmable ASIC Logic Cells: The Anti fuse, S					
	hnology, Practical Issues, Specifications, PREDP Benchmarks, F	PGA I	Econon	nics, A	Actel	
	CA, Altera Flex, Altera Max.	1.				
UNIT - III			cture H			
	Interconnects & Programmable ASIC Design Software: DC (
	at, Clock input, Power input, Xilinx I/O block, Other I/O Cells, A					
	Altera Max 5000 and 7000, Altera Max 9000, Altera FLEX,	Design	Syste	ms, L	og1c	
•	Half gate ASIC.	Ta	041140 II			
UNIT - IV			cture H			
	sign Entry and Logic Synthesis: Schematic Entry, Low level Design					
	synthesis example, A Comparator/MUX, Inside a Logic Synthesiz					
	og and Logic synthesis, VHDL and Logic Synthesis, Finite State Mac		•		погу	
UNIT - V	Synthesis, The Engine Controller, Performance Driven Synthesis, Optimization of the viterbi decoder. UNIT - V Lecture Hrs:					
	est and ASIC Construction: Types of Simulation, The Comparato				ogic	
	**			•	_	
systems, now	Logic Simulation Works, Cell Models, Delay Models, Static Ta	mmg	Anaiys	18, FO	1111111	

Simulation, Test and ASIC Construction: Types of Simulation, The Comparator/MUX Example, Logic Systems, How Logic Simulation Works, Cell Models, Delay Models, Static Timing Analysis, Formal Verification, Switch Level Simulation, Transistor Level Simulation, The importance of test, Boundary Scan Test, Faults, Faults Simulation, Automatic Test Pattern Generator, Scan Test, Built in Self-Test, A simple test Example, Physical Design, CAD Tools, System Partitioning, Estimating ASIC Size, Power Dissipation, FPGA Partitioning, Partitioning Methods

Textbooks:

- 1. Michael John Sebastian Smith, "Application Specific Integrated Circuits", Pearson Education, 2003.
- 2. L.J.Herbst, "Integrated Circuit Engineering", Oxford Science Publications, 1996.

Reference Books:

1. HimanshuBhatnagar, "Advanced ASIC Chip Synthesis using Synopsis Design Compiler", 2nd Edition, Kluwer Academic, 2001.

Course Code	RESEARCH METHODOLOGY AND IPR	L	T	P	C
23VSDMC01		3	0	0	3
	Semester		I		
Course Objectives:					
	appropriate research problem in their interesting domain.				
	ethical issues understand the Preparation of a research project	et thesis	s repor	t.	
	the Preparation of a research project thesis report				
	the law of patent and copyrights.				
	the Adequate knowledge on IPR				
`	CO): Student will be able to				
	arch related information				
2. Follow research					
	at today's world is controlled by Computer, Information Technol	ology, b	out tom	orrow	
	ruled by ideas, concept, and creativity.	. 11	-1- 0	_4:	:4 :-
	that when IPR would take such important place in growth of in apphasis the need of information about Intellectual Property Rigl				
	neral & engineering in particular.	ii to be	promo	teu an	long
	at IPR protection provides an incentive to inventors for further	research	work	and	
	R & D, which leads to creation of new and better products, and				
	wth and social benefits.	III turii	ormgs	aooat,	
UNIT - I	van die goeiar cenerius	Le	cture H	rs:	
	h problem, Sources of research problem, Criteria Characteri	stics of	a goo	d rese	earch
	electing a research problem, scope, and objectives of research				
	lutions for research problem, data collection, analysis, i				
instrumentations.	•	•			•
UNIT - II		Le	cture F	Irs:	
Effective literature st	tudies approaches, analysis Plagiarism, Research ethics, Effecti	ve tech	nical w	riting,	how
to write report, Pape	er Developing a Research Proposal, Format of research prop	osal, a	preser	ntation	and
assessment by a review	ew committee.				
UNIT - III		Le	cture H	lrs:	
	ual Property: Patents, Designs, Trade and Copyright. Pro-	ocess o	of Pate	enting	and
Development: tech	nological research, innovation, patenting, development.	Interna	ational	Scen	ario:
	ation on Intellectual Property. Procedure for grants of patents, P				
UNIT - IV			cture H		
	be of Patent Rights. Licensing and transfer of technology.	Patent	inforr	nation	and
databases. Geograph	ical Indications.				
UNIT - V			cture H		
-	in IPR: Administration of Patent System. New developments i		IPR of	Biolo	gical
	Software etc. Traditional knowledge Case Studies, IPR and IITs	S.			
Textbooks:					
	nd Wayne Goddard, "Research methodology: an introduction f	or scier	ice & e	engine	ering
students"	10. (M.1.11 4D. 1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1				
	nd Stuart Melville, "Research Methodology: An Introduction"				
Reference Books:					

1. Ranjit Kumar, 2nd Edition, "Research Methodology: A Step by Step Guide for beginners"

Halbert, "Resisting Intellectual Property", Taylor & Examp; Francis Ltd ,2007.
 Mayall, "Industrial Design", McGraw Hill, 1992.

- 4. Niebel, "Product Design", McGraw Hill, 1974.5. Asimov, "Introduction to Design", Prentice Hall, 1962.6. Robert P. Merges, Peter S. Menell, Mark A. Lemley, "Intellectual Property in New Technological Age", 2016.

Course Code	VI SI Tashnalagy I sh	L	T	P	С
23VSDPC01L	VLSI Technology Lab	0	0	4	2
	Semester		I		

- 1. To explain the VLSI Design Methodologies using any VLSI design tool.
- 2. To grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation

Course Outcomes (CO): Student will be able to

- 1. Design any logic circuit using CMOS transistor.
- 2. Use different software tools for analysis of circuits.
- 3. Design layouts to the CMOS circuits.
- 4. Use different software tools for analog layout

List of Experiments:

- ➤ The students are required to design the schematic diagrams using CMOS logic and to draw the layout diagrams to perform the experiments with the Industry standard EDA Tools with 180nm Technology.
- 1. Design and analysis of CMOS Inverter
- 2. Design and analysis of NAND and NOR Logic gates
- 3. Design and analysis of XOR and XNOR Logic gates
- 4. Design of AOI logic
- 5. Design and analysis of Full adder
- 6. Analysis of NMOS and PMOS characteristics
- 7. Design and analysis of Common source amplifier
- 8. Design and analysis of Common drain amplifier
- 9. Design of MOS differential amplifier
- 10. Design of two stage differential amplifier.
- 11. Design of Inverter Layout
- 12. Design of NAND/NOR Layout.

Note: Any TEN of the experiments are to be conducted

Software Required: i. Mentor Graphics/ Synopsis/ Cadence / Equivalent Industry Standard Software.

ii. Personal computer system with necessary software to run the programs and to Implement.

Course Code	CMOS ANALOG IC DESIGN LAB	L	T	P	C
23VSDPC02L		0	0	4	2
	Semester		I		

- 1. To explain the VLSI Design Methodologies using VLSI design tool.
- 2. To grasp the significance of various CMOS analog circuits in full-custom IC Design flow
- 3. To explain the Physical Verification in Layout Design
- 4. To fully appreciate the design and analyze of analog and mixed signal simulation
- 5. To grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation

Course Outcomes (CO): Student will be able to

- 1. Explain the VLSI Design Methodologies using VLSI design tool.
- 2. Grasp the significance of various CMOS analog circuits in full-custom IC Design flow
- 3. Explain the Physical Verification in Layout Design
- 4. Fully appreciate the design and analyze of analog and mixed signal simulation
- 5. Grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation

List of Experiments:

- ➤ The students are required to design and implement any **TEN** Experiments using CMOS 130nm Technology.
- The students are required to implement LAYOUTS of any SIX Experiments using CMOS 130nm Technology and Compare the results with Pre-Layout Simulation.
- 1. MOS Device Characterization and parametric analysis
- 2. Common Source Amplifier
- 3. Common Source Amplifier with source degeneration
- 4. Cascode amplifier
- 5. Simple current mirror
- 6. Cascode current mirror.
- 7. Wilson current mirror.
- 8. Differential Amplifier
- 9. Operational Amplifier
- 10. Sample and Hold Circuit
- 11. Direct-conversion ADC
- 12. R-2R Ladder Type DAC.

Lab Requirements:

Software:

Mentor Graphics - Pyxis Schematic, IC Station, Calibre, ELDO Simulator

Hardware:

Personal Computer with necessary peripherals, configuration and operating System.

AUDIT COURSE-I

Course Code		L	Т	P	С
23VSDAC01a	ENGLISH FOR RESEARCH PAPER WRITING	3	0	0	3
23 (50) 10010	Semester	3	I	U	
Course Objective					
	and the essentials of writing skills and their level of readability				
	out what to write in each section				
	ualitative presentation with linguistic accuracy				
	s (CO): Student will be able to				
2. Analyze and w	significance of writing skills and the level of readability rite title, abstract, different sections in research paper kills needed while writing a research paper				
UNIT - I		Lec	ture H	rs:	
L L	esearch Paper- Planning and Preparation- Word Order- Useful Phra	ases - I	Breakin	g up	Long
	aring Paragraphs and Sentences-Being Concise and Removing				
Ambiguity.			•		
UNIT - II		Le	cture H	Irs:	
	nents of a Research Paper- Abstracts- Building Hypothesis-Resear	ch Pro	blem -	High	light
	g and Criticizing, Paraphrasing and Plagiarism, Cauterization.				
UNIT - III			ture H		
	ew of the Literature - Methodology - Analysis of the Data-	Findin	gs - D	Discus	sion-
Conclusions-Reco	ommendations.				
UNIT - IV		Lec	ture H	rs:	
Key skills needed	for writing a Title, Abstract, and Introduction.				
UNIT - V		Lec	ture H	rs:	
Appropriate lang	uage to formulate Methodology, incorporate Results, put forth	Argu	ments	and	draw
Conclusions.					
Suggested Readi					
	06) Writing for Science, Yale University Press (available on Google	e Book	s).		
	n of Engineering & Technology PG Courses [Volume-I]				
	How to Write and Publish a Scientific Paper, Cambridge University			_	
	998), Handbook of Writing for the Mathematical Sciences, SIAM. H				
	ork , English for Writing Research Papers, Springer New York	Dord	recht I	Heide	berg
London, 2011.					

Course Code	DISASTER MANAGEMENT	L	T	P	С
23VSDAC01b	DISASTER MANAGEMENT	3	0	0	3
	Semester		I		

- 1. Learn to demonstrate critical understanding of key concepts in disaster risk reduction and humanitarian response.
- 2. Critically evaluated are asterisk reduction and humanitarian response policy and practice from Multiple perspectives.
- 3.Developanunderstandingofstandardsofhumanitarianresponseandpracticalrelevanceinspecific types of disasters and conflict situations
- 4. Criticallyunderstandthestrengthsandweaknesses of disastermanagement approaches, planning and programming in different countries, particularly their home country or the countries they work in

Course Outcomes (CO): Student will be able to

UNIT - I Lecture Hrs:

Introduction:

Disaster:Definition,FactorsandSignificance;DifferenceBetweenHazardandDisaster;Naturaland Manmade Disasters: Difference, Nature, Types and Magnitude.

Disaster Prone Areas in India:

Study of Seismic Zones; Areas Prone to Floods and Droughts, Landslides and Avalanches; Areas Prone to Cyclonic and Coastal Hazards with Special Reference to Tsunami; Post- Disaster Diseases and Epidemics.

UNIT - II Lecture Hrs:

Repercussions of Disasters and Hazards:

Economic Damage, Loss of Human and Animal Life, Destruction of Ecosystem. Natural Disasters: Earthquakes, Volcanisms, Cyclones, Tsunamis, Floods, Droughts and Famines, Landslides and Avalanches, Man-made disaster: Nuclear Reactor Meltdown, Industrial Accidents, Oil Slicks and Spills, Outbreaks of Disease and Epidemics, War and Conflicts.

UNIT - III Lecture Hrs:

Disaster Preparedness and Management:

Preparedness: Monitoring of Phenomena Triggering A Disaster or Hazard; Evaluation of Risk: Application of Remote Sensing, Data from Meteorological and Other Agencies, Media Reports: Governmental and Community Preparedness.

UNIT - IV Lecture Hrs:

Risk Assessment Disaster Risk:

Concept and Elements, Disaster Risk Reduction, Global and National Disaster Risk Situation. Techniques of Risk Assessment, Global Co-Operation in Risk Assessment and Warning, People's Participation in Risk Assessment. Strategies for Survival.

UNIT - V Lecture Hrs:

Meaning, Conceptand Strategies of Disaster Mitigation, Emerging Trends In Mitigation. Structural Mitigation and Non-Structural Mitigation, Programs of Disaster Mitigation in India.

Suggested Reading:

- 1. R.Nishith, Singh AK, "Disaster Management in India: Perspectives, issues and strategies
- 2. "'New Royal book Company. Sahni, Pardeep Et.Al. (Eds.)," Disaster Mitigation Experiences And Reflections", Prentice Hall Of India, New Delhi.
- 3. GoelS.L.,DisasterAdministrationAndManagementTextAndCaseStudies",Deep&Deep Publication Pvt. Ltd., New Delhi.

0 0 1		т	T	D	
Course Code	SANSKRITFOR TECHNICAL KNOWLEDGE	L	T 0	P	C
23VSDAC01c		3	0	3	
	Semester		I		
Course Objective					
	vorking knowledge in illustrious Sanskrit, the scientific language in	n the w	orld		
	of Sanskrit to improve brain functioning				
•	of Sanskrittodevelopthelogicinmathematics, science & other subjects	enhanc	ing the	e mer	nory
power		_			
	neering scholars equipped with Sanskrit will be able to explore the	huge			
	ge from ancient literature				
	s (CO): Student will be able to				
	nding basic Sanskrit language				
	anskrit literature about science &technology can be understood				
	a logical language will help to develop logic in students				
UNIT - I		Lec	cture H	rs:	
Alphabets in Sans	krit,				
UNIT - II		Le	cture H	rs:	
Past/Present/Futur	re Tense, Simple Sentences				
UNIT - III		Leo	cture H	rs:	
Order, Introduction	n of roots				
UNIT - IV		Leo	cture H	rs:	
Technical informa	ation about Sanskrit Literature	•			
UNIT - V		Leo	cture H	rs:	
Technical concept	s of Engineering-Electrical, Mechanical, Architecture, Mathematic	cs.			
Suggested Reading					
	m" –Dr. Vishwas, Sanskrit-Bharti Publication, New Delhi				
	f Sanskrit" Prathama Deeksha- VempatiKutumbshastri, RashtriyaS	anskrit			
	Delhi Publication				
3."India's Gloriou	s Scientific Tradition" Suresh Soni, Ocean books (P) Ltd., New De	elhi			

Course Code	CMOS MIXED SIGNAL IC DESIGN	L	T	P	С
23VSDPC03	CIVIOS IVIIAED SIGNAL IC DESIGN	3	0	0	3
	Semester		II		
Course Objecti					
	onstrate first order filter with least interference				
consider	nd the concept of phase locked loop for designing PLL application ring non ideal effects.				•
	ign different A/D, D/A, modulators, demodulators and different	ent filte	er for	real	time
applicat					
	nes (CO): Student will be able to				
	strate first order filter with least interference			_	
	the concept of phase locked loop for designing PLL application with	minim	um jitte	er by	
	ring non ideal effects.	1 4 .		11 41 -	
	different A/D, D/A, modulators, demodulators and different filter for		ne app cture H		ns
UNIT - I					
-	citor Circuits: Introduction to Switched Capacitor circuits- basic by Non-ideal effects in switched capacitor circuits, Switched capacito	_			
•	naring, biquad filters.	n mieg	rators,	mst (JI dei
UNIT - II	iaring, olquad filters.	Le	cture H	re.	
	Loop (PLL): Basic PLL topology, Dynamics of simple PLL, C				Lock
	se/Frequency detector and charge pump, Basic charge pump PLL, N				
	ealities, Jitter in PLLs, Delay locked loops, applications.	OII-IGCa	.1 (11(0)	.5 111 1	LL3-
UNIT - III	anties, sitter in 1225, 20th rocked 100ps, applications.	Lec	ture H	rs:	
Data Converte	r: Fundamentals DC and dynamic specifications, Quantization r	noise. N	Vauist	rate	D/A
	coder based converters, Binary-Scaled converters, Thermometer-		~ 1		
converters.	•			•	
UNIT - IV		Lec	ture H	rs:	
A to D Conver	ters: Nyquist Rate A/D Converters Successive approximation con	verters.	Flash	conve	erter,
	onverters, Interpolating A/D converters, Folding A/D converters, P	ipeline	d A/D	conver	ters,
Sigma Delta A/I	O coverters, Time- interleaved converters.				

UNIT - V Lecture Hrs:

Oversampling Converters: Noise shaping modulators, Decimating filters and interpolating filters, Higher order modulators, Delta sigma modulators with multi bit quantizers, Delta sigma D/A.

Textbooks:

- 1. Design of Analog CMOS Integrated Circuits- BehzadRazavi, TMH Edition, 2002
- 2. CMOS Analog Circuit Design Philip E. Allen and Douglas R. Holberg, Oxford University Press, International Second Edition/Indian Edition, 2010.
- 3. Analog Integrated Circuit Design- David A. Johns, Ken Martin, Wiley Student Edition, 2013.

- 1. CMOS Integrated Analog-to- Digital and Digital-to-Analog converters- Rudy Van De Plassche, Kluwer Academic Publishers, 2003
- 2. Understanding Delta-Sigma Data converters-Richard Schreier, Wiley Inter science, 2005.
- 3. CMOS Mixed-Signal Circuit Design R. Jacob Baker, Wiley Interscience, 2009.

Course Code CMOS DIG	CMOS DICITAL IC DESIGN	L	T	P	С
23VSDPC04	CMOS DIGITAL IC DESIGN	3	0	0	3
Semester	Semester				

- 1. To understand the fundamental properties of digital Integrated circuits using basic MOSFET equations and to develop skills for various logic circuits using CMOS related design styles.
- 2. The course also involves analysis of performance metrics.
- 3. To teach fundamentals of CMOS Digital integrated circuit design such as importance of Pseudo logic, Combinational MOS logic circuits and Sequential MOS logic circuits.
- 4. To teach the fundamentals of Dynamic logic circuits and basic semiconductor memories which are the basics for the design of high performance digital integrated circuits.

Course Outcomes (CO): Student will be able to

- 1. Demonstrate advanced knowledge in Static and dynamic characteristics of CMOS,
- 2. Estimate Delay and Power of Adders circuits.
- 3. Classify different semiconductor memories.
- 4. Analyze, design and implement combinational and sequential MOS logic circuits.
- 5. Analyze complex engineering problems critically in the domain of digital IC design for conducting research.
- 6. Solve engineering problems for feasible and optimal solutions in the core area of digital ICs

UNIT - I Lecture Hrs

MOS Design Pseudo NMOS Logic: Inverter, Inverter threshold voltage, Output high voltage, Output Low voltage, Gain at gate threshold voltage, Transient response, Rise time, Fall time, Pseudo NMOS logic gates, Transistor equivalency, CMOS Inverter logic.

UNIT - II Lecture Hrs:

Combinational MOS Logic Circuits: MOS logic circuits with NMOS loads, Primitive CMOS logic gates—NOR & NAND gate, Complex Logic circuits design—Realizing Boolean expressions using NMOS gates and CMOS gates, AOI and OIA gates, CMOS full adder, CMOS transmission gates, Designing with Transmission gates.

UNIT - III Lecture Hrs:

Sequential MOS Logic Circuits: Behavior of bistable elements, SR Latch, Clocked latch and flip flop circuits, CMOS D latch and edge triggered flip-flop.

UNIT - IV Lecture Hrs:

Dynamic Logic Circuits: Basic principle, Voltage Bootstrapping, Synchronous dynamic pass transistor circuits, Dynamic CMOS transmission gate logic, High performance Dynamic CMOS circuits.

UNIT - V Lecture Hrs:

Semiconductor Memories: Types, RAM array organization, DRAM – Types, Operation, Leakage currents in DRAM cell and refresh operation, SRAM operation Leakage currents in SRAM cells, Flash Memory-NOR flash and NAND flash.

Textbooks:

- 1. Neil Weste, David Harris, "CMOS VLSI Design: A Circuits and Systems Perspective", 4th Edition, Pearson, 2010
- 2. Digital Integrated Circuit Design Ken Martin, Oxford University Press, 2011.
- 3. CMOS Digital Integrated Circuits Analysis and Design Sung-Mo Kang, Yusuf Leblebici, TMH, 3rd Edition, 2011.

- 1.Introduction to VLSI Systems: A Logic, Circuit and System Perspective Ming-BO Lin, CRC Press, 2011
- 2. Digital Integrated Circuits A Design Perspective, Jan M.Rabaey, AnanthaChandrakasan, Borivoje Nikolic, 2ndEdition, PHI.

Course Code	PHYSICAL DESIGN AUTOMATION	L	T	P	С		
23VSDPE03a	Program Elective – III	3	0	0	3		
	Semester		II				
Course Objectiv	es:						
1. To under	stand relation between automation algorithms and constraints posed	l by VI	SI tech	nolog	y.		
	algorithms to meet critical design parameters.						
3. To design	n area efficient logics by employing different routing algorithms and	d shape	functi	ons.			
	ate and synthesis different combinational and sequential logics.						
	es (CO): Student will be able to						
	nd relation between automation algorithms and constraints posed by	VLSI	technol	ogy.			
	orithms to meet critical design parameters.						
	ea efficient logics by employing different routing algorithms and sh	ape fur	ections.				
	and synthesis different combinational and sequential logics.						
UNIT - I			Lecture				
	utomation Tools: Algorithms and system design, Structural and	logic o	design,	Trans	istor		
	out design, Verification methods, Design management tools.						
UNIT - II			Lecture				
Formulation met	ction, placement and routing, Design rules, symbolic layout, Apphods, Algorithms for constrained graph compaction, Circuit represent algorithms, Partitioning algorithms.						
UNIT - III		I	ecture	Hrs:			
	and routing: Floor planning concepts, Shape functions and flooting, Channel routing, global routing and its algorithms.	r plann	ing siz	ing, L	ocal		
UNIT - IV		I	ecture	Hrs:			
	Logic Synthesis: Gate level and switch level modeling and single synthesis, ROBDD principles, implementation, construction esis.						
UNIT - V		I	Lecture	Hrs:			
High-Level Synt	High-Level Synthesis: Hardware model for high level synthesis, internal representation of input algorithms, Allocation, assignment and scheduling, scheduling algorithms, Aspects of assignment, High level						
Textbooks:							
1. S.H. Gerez, Al	gorithms for VLSI Design Automation, John Wiley, 1998.						
2. N.A. Sherwani	, Algorithms for VLSI Physical Design Automation, (3/e), Kluwer,	1999.					
Reference Books	S:						
	oussef, VLSI Physical Design Automation, World scientific, 1999.						
2. M.Sarrafzadeh	, Introduction to VLSI Physical Design, McGraw Hill (IE), 1996.						

Course Code	SEMICONDUCTOR MEMORY DESIGN AND TESTING	L	T	P	С	
23VSDPE03b	Program Elective – III	3	0	0	3	
23 1 3 2 1 2 0 3 0	Semester		II			
Course Objectiv						
	estand different types of memories, their architectural and differen	nt nack	ing tec	hniana	es of	
memories	* *	п раск	ing tee	imique	05 01	
	fault models for memory testing.					
	ze different parameters that lead malfunctioning of memories.					
	reliable memories with efficient architecture to improve processes	times	and po	wer.		
	es (CO): Student will be able to					
	nowledge regarding different types of memories, their architectural	and d	ifferent	packi	ng	
techniques of men				1	υ	
	dels for memory testing.					
3. Analyze differe	ent parameters that lead malfunctioning of memories.					
4. Design reliable	e memories with efficient architecture to improve processes times an	nd pow	er.			
UNIT - I		Le	cture H	rs:		
Random Access	Memory Technologies: SRAM – SRAM Cell structures, MOS SF	RAM A	rchitec	ture, l	MOS	
CMOS DRAM, DRAM, Advance UNIT - II	technologies, Application specific SRAMs, DRAM – DRAM to DRAM cell theory and advanced cell structures, BICMOS DRAM ed DRAM design and architecture, Application specific DRAM.	M, so	ft error	failui Irs:	re in	
EPROM, Floatin	emories: Masked ROMs, High density ROM, PROM, Bipolar is gate EPROM cell, One time programmable EPROM, EEPROM Non-volatile SRAM, Flash Memories (EPROM or EEPROM), a	1, EEP	ROM 1	echno	logy	
UNIT - III		Le	cture H	rs:		
RAM fault mode memory modeling	Modeling Testing and Memory Design for Testability and Fault eling, Electrical testing, Pseudo Random testing, Megabit DRA g and testing, IDDQ fault modeling and testing, Application specific IST techniques for memory.	M Tes	ting, n			
UNIT - IV		Le	cture H	rs:		
and mechanism, Reliability, Reliability, Relia Event Phenomen Issues, Radiation	Semiconductor Memory Reliability and Radiation Effects: General reliability issues RAM failure modes and mechanism, Non-volatile memory reliability, reliability modeling and failure rate prediction, Design for Reliability, Reliability Test Structures, Reliability Screening and qualification, Radiation effects, Single Event Phenomenon (SEP), Radiation Hardening techniques, Radiation Hardening Process and Design Issues, Radiation Hardened Memory characteristics, Radiation Hardeness Assurance and Testing, Radiation					
UNIT - V	r Level Radiation Testing and Test structures.	Ιρ	cture H	rs.		
Advanced Memor Ferroelectric RA Experimental me	ory Technologies and High-density Memory Packing Technologies Ms (FRAMs), GaAs FRAMs, Analog memories, magneto resist emory devices, Memory Hybrids and MCMs (2D), Memory Statesting and reliability issues, Memory cards, High Density Memor	ies stive R acks a	AMs (MRA CMs ((3D),	

Textbooks:

1. Semiconductor Memories Technology – Ashok K. Sharma, 2002, Wiley.

2. Advanced Semiconductor Memories – Architecture, Design and Applications - Ashok K. Sharma, 2002, Wiley.

Reference Books:

1. Modern Semiconductor Devices for Integrated Circuits – Chenming C Hu, First Edition. Prentice all.

Course Code	TESTING & TESTABILITY	L	T	P	C
23VSDPE03c	Program Elective – III	3	0	0	3
	Semester		II		
Course Objectiv	ves:				
1. To unde	erstand the concepts of faults and testing in SoC				
2. To imple	ement the faults using simulation tools				
3. To analy	ze BIST systems				
Course Outcom	es (CO): Student will be able to				
1. Underst	and the concepts of faults and testing in SoC				
2. Impleme	nt the faults using simulation tools				
3. Analyze	BIST systems				
UNIT - I		Le	cture H	rs:	
INTRODUCTION	ON TO TEST AND DESIGN FOR TESTABILITY (DFT) FUND)AMF	NTAL	S:	
Modeling: Mode	ling Digital Circuits at Logic Level, Register Level and Structural M	lodels.	Levels	of	
Modeling. Logic	Simulation: Types of Simulation, Delay Models, Element Evaluatio	n, Haz	zard De	tection	1,
Gate Level Even	t Driven Simulation.				
UNIT - II		Le	cture H	lrs:	
	LING: Logic Fault Models, Fault Detection and Redundancy, Faul				
	Stuck and Multiple Stuck Fault Models. Fault Simulation Application	ons, G	eneral T	Γechni	ques
for Combination	al Circuits.				
UNIT - III		Le	cture H	rs:	
	SINGLE STUCK FAULTS (SSF): Automated Test Pattern Gener				
	national and Sequential Circuits, Functional Testing With Specifi		lt Mode	els. V	ector
	G Vectors, Formats, Compaction and Compression, Selecting ATPG	Tool.			
UNIT - IV			cture H		
	TESTABILITY: Testability Trade-Offs, Techniques. Scan Arc				
	nd Absorbability, Generic Boundary Scan, Full Integrated Scan,				
_	Level and System Level DFT Approaches. Boundary Scans S	tanda	rds. Co	mpres	ssion
	erent Techniques, Syndrome Test and Signature Analysis.				
UNIT - V			cture H		
	F-TEST (BIST): BIST Concepts and Test Pattern Generation. Spec				
	TS, LOCST, STUMPS, CBIST, CEBS, RTD, SST, CATS, CSTP,				
	BIST Concepts and Design for Self-Test at Board Level. MEM				(ST):
	chitectures and Techniques Introduction to Memory Test, JTAG Tes	ting F	eatures.		
Textbooks:					
	ovici, Melvin A. Breur, Arthur D.Friedman, Digital Systems Testin	ng and	Testab	ole De	sign,
Jaico Publishing	House, 2001.				

- 2. M.L. Bushnell, V. D. Agrawal, "Essentials of Electronic Testing for Digital, Memory and Mixed Signal VLSI Circuits", Kluwer Academic Pulishers.

- 1. P.K. Lala, "Digital Circuits Testing and Testability", Academic Press.
- 2. Alfred Crouch, Design for Test for Digital ICs & Embedded Core Systems, Prentice Hall.
- 3. Robert J.Feugate, Jr., Steven M.Mentyn, Introduction to VLSI Testing, Prentice Hall, Englehood Cliffs.

Course Code	LOW POWER VLSI DESIGN	L	T	P	C			
23VSDPE04a	Program Elective – IV	3	0	0	3			
	Semester		II					
Course Objectiv	Course Objectives:							
1. To unde	rstand the concepts of velocity saturation, Impact Ionization a	nd Ho	t Electr	on E	ffect			
2. To imple	ment Low power design approaches for system level and circuit lev	el mea	sures.					
	n low power adders, multipliers and memories for efficient design of	f syste	ms.					
	es (CO): Student will be able to							
1. Understa	and the concepts of velocity saturation, Impact Ionization and	Hot E	lectron	Effe	et			
	nt Low power design approaches for system level and circuit level a							
3. Design lo	ow power adders, multipliers and memories for efficient design of s	ystems.						
UNIT - I			cture H					
Fundamentals:	Need for Low Power Circuit Design, Sources of Power Dissipation	n – St	atic and	l Dyn	amic			
	n, Short Circuit Power Dissipation, Glitching Power Dissipation,							
	Barrier Lowering and Punch Through, Surface Scattering, Velo	ocity S	aturatio	n, In	ıpact			
Ionization, Hot E	lectron Effect.							
UNIT - II			cture H					
Low-Power Des	sign Approaches: Low-Power Design through Voltage Scaling	g - V'	TCMO	S circ	cuits,			
	ts, Architectural Level Approach –Pipelining and Parallel Processin							
•	nimization Approaches: System Level Measures, Circuit Level	Measi	ures, M	I ask	level			
Measures.								
UNIT - III			cture H					
0	ow-Power Adders: Introduction, Standard Adder Cells, CMOS							
	ders, Carry Look Ahead Adders, Carry Select Adders, Carry Sav				_			
	gn Techniques - Trends of Technology and Power Supply Volt	age, Lo	ow-Vol	tage I	∠ow-			
Power Logic Styl	es.							
UNIT - IV			cture H					
_	ow-Power Multipliers: Introduction, Overview of Multiplication				•			
	aun Multiplier, Baugh Wooley Multiplier, Booth Multiplier, Intro	ductior	ı to Wa	llace	Tree			
Multiplier.		1						
UNIT - V			cture H					
	ow-Power Memories: Basics of ROM, Low-Power ROM Techno							
•	ROMs, Basics of SRAM, Memory Cell, Precharge and Equalization							
	gies, Basics of DRAM, Self-Refresh Circuit, Future Trend and Dev	elopme	ent of D	RAM	•			
Textbooks:								
	Integrated Circuits – Analysis and Design – Sung-Mo Kang, Yusuf							
_	Low-Power VLSI Subsystems – Kiat-Seng Yeo, Kaushik R	Roy, T	MH Pı	ofessi	onal			
Engineering.								
Reference Books			GE G =					
	VLSI Systems: A Logic, Circuit and System Perspective – Ming-F			ress.				
	MOS Design – AnanthaChandrakasan, IEEE Press/Wiley Internation			2000				
3. Low Power CN	MOS VLSI Circuit Design – Kaushik Roy, Sharat C. Prasad, John V	<u> 11ey &</u>	Sons,	<u> 2000</u>				

Course Code	IOT AND ITS APPLICATIONS	L	T	P	С
23VSDPE04b	Program Elective – IV	3	0	0	3
	Semester		II		

- 1. To apply the Knowledge in IOT Technologies and Data management.
- 2. To determine the values chains Perspective of M2M to IOT.
- 3. To implement the state of the Architecture of an IOT.
- 4. To compare IOT Applications in Industrial & real world.
- 5. To demonstrate knowledge and understand the security and ethical issues of an IOT.

Course Outcomes (CO): Student will be able to

- 1. Apply the Knowledge in IOT Technologies and Data management.
- 2. Determine the values chains Perspective of M2M to IOT.
- 3. Implement the state of the Architecture of an IOT.
- 4. Compare IOT Applications in Industrial & real world.
- 5. Demonstrate knowledge and understand the security and ethical issues of an IOT.

UNIT - I Lecture Hrs:

Fundamentals of IoT: Evolution of Internet of Things, Enabling Technologies, IoT Architectures, one M2M, IoT World Forum (IoTWF) and Alternative IoT models, Simplified IoT Architecture and Core IoT Functional Stack, Fog, Edge and Cloud in IoT, Functional blocks of an IoT ecosystem, Sensors, Actuators, Smart Objects and Connecting Smart Objects.

IoT Platform overview: Overview of IoT supported Hardware platforms such as: Raspberry pi, ARM Cortex Processors, Arduino and Intel Galileo boards.

UNIT - II Lecture Hrs:

IoT Protocols: IT Access Technologies: Physical and MAC layers, topology and Security of IEEE 802.15.4, 802.15.4g, 802.15.4e, 1901.2a, 802.11ah and Lora WAN, Network Layer: IP versions, Constrained Nodes and Constrained Networks, Optimizing IP for IoT: From 6LoWPAN to 6Lo, Routing over Low Power and Lossy Networks, Application Transport Methods: Supervisory Control and Data Acquisition, Application Layer Protocols: CoAP and MQTT.

UNIT - III Lecture Hrs:

Design and Development: Design Methodology, Embedded computing logic, Microcontroller, System on Chips, IoT system building blocks, Arduino, Board details, IDE programming, Raspberry Pi, Interfaces and Raspberry Pi with Python Programming.

UNIT - IV Lecture Hrs:

Data Analytics and Supporting Services: Structured Vs Unstructured Data and Data in Motion Vs Data in Rest, Role of Machine Learning – No SQL Databases, Hadoop Ecosystem, Apache Kafka, Apache Spark, Edge Streaming Analytics and Network Analytics, Xively Cloud for IoT, Python Web Application Framework, Django, AWS for IoT, System Management with NETCONF-YANG.

UNIT - V Lecture Hrs:

Case Studies/Industrial Applications: IoT applications in home, infrastructures, buildings, security, Industries, Home appliances, other IoT electronic equipments. Use of Big Data and Visualization in IoT, Industry 4.0 concepts. Sensors and sensor Node and interfacing using any Embedded target boards (Raspberry Pi / Intel Galileo/ARM Cortex/ Arduino).

Textbooks:

- 1. IoT Fundamentals: Networking Technologies, Protocols and Use Cases for Internet of Things, David Hanes, Gonzalo Salgueiro, Patrick Grossetete, Rob Barton and Jerome Henry, Cisco Press, 2017.
- 2. Internet of Things A hands-on approach, ArshdeepBahga, Vijay Madisetti, Universities Press, 2015

- 1. The Internet of Things Key applications and Protocols, Olivier Hersent, David Boswarthick, Omar Elloumi and Wiley, 2012 (for Unit 2).
- 2. "From Machine-to-Machine to the Internet of Things Introduction to a New Age of Intelligence", Jan Holler, VlasiosTsiatsis, Catherine Mulligan, Stamatis, Karnouskos, Stefan Avesand. David Boyle and Elsevier, 2014.
- 3. Architecting the Internet of Things, Dieter Uckelmann, Mark Harrison, Michahelles and Florian (Eds), Springer, 2011.

Course Code	VLSI SIGNAL PROCESSING	L	Т	P	С	
23VSDPE04c	Program Elective – IV	3	0	0	3	
	Semester	II				
Course Objectiv	es:					
1. To study	the existing architectures suitable for VLSI.					
2. To under	stand the concepts of folding and unfolding algorithms and applicat	ions.				
	n new architectures suitable for VLSI.					
4. To imple	ment fast convolution algorithms.					
Course Outcome	es (CO): Student will be able to					
1. Study the exist	sting architectures suitable for VLSI.					
2. Understand the	e concepts of folding and unfolding algorithms and applications.					
	chitectures suitable for VLSI.					
4. Implement fast	convolution algorithms.					
UNIT - I		Le	cture H	rs:		
Introduction to	DSP: Typical DSP algorithms, DSP algorithms benefits, Represent	ation o	f DSP	algori	thms	
	Parallel Processing Introduction, Pipelining of FIR Digital filter					
	Parallel Processing for Low Power Retiming Introduction, Def	initions	s and	Prope	rties,	
	f Inequalities, Retiming Techniques.					
UNIT - II			cture H			
0	nfolding: Folding- Introduction, Folding Transform, Register m				-	
	ration in folded architectures, folding of Multirate systems Unfo					
_	nfolding, Properties of Unfolding, critical Path, Unfolding and Re	etiming	g, Appl	icatio	ns of	
Unfolding.						
UNIT - III			cture H			
	cture Design: Introduction, Systolic Array Design Methodolog					
	eduling Vector, Matrix Multiplication and 2D Systolic Array Des	ign, Sy	stolic 1	Desig	1 for	
	ations contain Delays.	-				
UNIT - IV			cture H			
	n: Introduction – Cook - Toom Algorithm – Winogard algorithm	– Iterat	ed Cor	voluti	on –	
	on – Design of Fast Convolution algorithm by Inspection.					
UNIT - V			cture H			
	ign: Digital lattice filter structures, bit level arithmetic, architectur					
	gth reduction, synchronous, wave and asynchronous pipe lin			Vs P	ower	
Consumption, Po	wer Analysis, Power Reduction techniques, Power Estimation Appr	roaches	5.			
Toythooke						

Textbooks:

- 1. Keshab K. Parthi, VLSI Digital Signal Processing- System Design and Implementation, Wiley Inter Science, 1998.
- 2. Kung S. Y, H. J. While House, T. Kailath ,VLSI and Modern Signal processing , Prentice Hall, 1985.

- 1. Jose E. France, Yannis Tsividis, Design of Analog Digital VLSI Circuits for Telecommunications and Signal Processing, Prentice Hall, 1994.
- 2. Medisetti V. K, VLSI Digital Signal Processing, IEEE Press (NY), 1995.

Course Code	CMOC DICITAL IC DECICAL AD	L	T	P	С		
23VSDPC03L	CMOS DIGITAL IC DESIGN LAB	0	0	4	2		
Semester			I	I			

- 1.To explain the VLSI Design Methodologies using any VLSI design tool.
- 2. To grasp the significance of various design logic Circuits in full-custom IC Design.
- 3. To explain the Physical Verification in Layout Extraction.
- 4. To fully appreciate the design and analyze of CMOS Digital Circuits.
- 5. To grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation.

Course Outcomes (CO): Student will be able to

- 1. Explain the VLSI Design Methodologies using any VLSI design tool.
- 2. Grasp the significance of various design logic Circuits in full-custom IC Design.
- 3. Explain the Physical Verification in Layout Extraction.
- 4. Fully appreciate the design and analyze of CMOS Digital Circuits.

Grasp the Significance of Pre-Layout Simulation and Post-Layout Simulation.

List of Experiments:

- ➤ The students are required to design and implement the Circuit and Layout of any **TEN** Experiments using CMOS 130nm Technology.
- 1. Inverter Characteristics.
- 2. NAND and NOR Gate
- 3. XOR and XNOR Gate
- 4. 2:1 Multiplexer
- 5. Full Adder
- 6. RS-Latch
- 7. Clock Divider
- 8. JK-Flip Flop
- 9. Synchronous Counter
- 10. Asynchronous Counter
- 11.Static RAM Cell
- 12. Dynamic Logic Circuits
- 13. Linear Feedback Shift Register

Lab Requirements:

Software:

Mentor Graphics Tool/ Cadence/ Synopsys/Industry Equivalent Standard Software

Hardware:

Personal Computer with necessary peripherals, configuration and operating System.

Course Code	CMOC Mined Circul Lab	L	T	P	С		
23VSDPC04L	CMOS Mixed Signal Lab	0	0	4	2		
Semester			I	I			

- 1. To design and simulate op-amp for given specifications
- 2. To design and simulate data converter for given specifications
- 3. To design and simulate PLL and VCO for given specifications
- 4. To understand the Significance of Pre-Layout Simulation and Post-Layout Simulation.

Course Outcomes (CO): Student will be able to

- 1. Design and simulate op-amp for given specifications
- 2. Design and simulate data converter for given specifications
- 3. Design and simulate PLL and VCO for given specifications
- 4. Understand the Significance of Pre-Layout Simulation and Post-Layout Simulation.

List of Experiments:

- ➤ The students are required to design and implement the Circuit and Layout of any **TEN** Experiments using CMOS 130nm Technology.
- 1. Analog Circuits Simulation using Spice.
- 2. Mixed Signal Simulation Using Mixed Signal Simulators.
- 3. Layout Extraction for Analog & Mixed Signal Circuits.
- 4. Parasitic Values Estimation from Layout.
- 5. Layout Vs Schematic.
- 6. Net List Extraction.
- 7. Design Rule Checks.
- 8. Layouts of All the circuits Designed and Simulated
- 9.Design of PLL
- 10. Fully compensated op-amp with resistor and miller compensation

Lab Requirements:

Software:

Mentor Graphics Tool/ Cadence/ Synopsys/Industry Equivalent Standard Software

Hardware:

Personal Computer with necessary peripherals, configuration and operating System.

References:

- 1. David A johns, Ken Martin, Analog Integrated Circuit Design, Wiley, 2008.
- 2. R. Gregorian and G.C Ternes, Analog MOS Integrated Circuits for Signal Processing, Wiley, 1986.
- 3. Roubik Gregorian, Introduction to CMOS OpAmp and Comparators, Wiley, 1999.
- 4. Alan Hastlings, The art of Analog Layout, Wiley, 2005.

AUDIT COURSE-II

0 0 1	1	т т	T	D	<u> </u>		
Course Code	PEDAGOGY STUDIES	<u>L</u>	T	P	<u>C</u>		
23VSDAC02a		3	0	0	3		
Semester			II				
Course Objectiv							
	1. Reviewexistingevidenceonthereviewtopictoinformprogrammedesignandpolicy making undertaken						
	TD, other agencies and researchers.						
	critical evidence gaps to guide the development.						
	es (CO): Student will be able to	. 1	1 .				
	calpracticesarebeingusedbyteachersinformalandinformalclassrooms	in dev	eloping	,			
countries?	1						
	dence on the effectiveness of these pedagogical practices, in what						
	d with what population of learners? reducation (curriculumandpracticum) andtheschoolcurriculumand g	nidono	a matar	iola b	act		
support effective		guiuanc	e mater	iais o	281		
UNIT - I	pedagogy:	Lo	cture H	ro.			
	d Methodology: Aims and rationale, Policy back ground, Cond				and		
	cories of learning, Curriculum, Teachereducation. Conceptual framew						
	hodology and Searching.	OIK,IC	scarcii	quest	10113•		
UNIT - II	nodotogy and beatering.	Le	Lecture Hrs:				
	iew: Pedagogical practices are being used by teachers in formal and				ns in		
	ries. Curriculum, Teacher education.	a miori	inai ora	351001	10 111		
UNIT - III	,	Lec	Lecture Hrs:				
Evidence on the effectiveness of pedagogical practices, Methodology for the indepth stage: quality assessment of							
included studies. How can teacher education (curriculumandpracticum) and the scho curriculum and guidance							
materials best support effective pedagogy? Theory of change. Strength and nature of th body of evidence for							
effective pedagogical practices. Pedagogic theory and pedagogical approaches. Teachers' attitudes and							
beliefs and Pedag	ogic strategies.						
UNIT - IV		Lec	Lecture Hrs:				
Professional development: Alignment with classroom practices and follow-up support, Peer support,							
	Support from the head eacher and the community. Curriculum and assessment, Barriers to learning: limited						
resources and lar	ge class sizes						

UNIT - V Lecture Hrs:

Researchgapsandfuturedirections: Researchdesign, Contexts, Pedagogy, Teachereducation, Curriculum and assessment, Dissemination and research impact.

Suggested Reading:

- 1. AckersJ, HardmanF(2001)ClassroominteractioninKenyanprimaryschools, Compare, 31 (2): 245-261.
- 2. AgrawalM(2004)Curricularreforminschools:Theimportanceofevaluation,Journalof
- 3. Curriculum Studies, 36 (3): 361-379.
- 4. AkyeampongK(2003) Teacher training in Ghana does it count? Multi-site teachereducation research project (MUSTER) country report 1. London: DFID.
- 5. Akyeampong K, LussierK, PryorJ, Westbrook J (2013)Improving teaching and learning of basic maths and reading in Africa: Does teacherpreparation count?International Journal Educational Development, 33 (3): 272–282.
- 6. Alexander RJ(2001) Culture and pedagogy: International comparisons in primary education. Oxford and Boston: Blackwell. Chavan M (2003)ReadIndia: A mass scale, rapid, 'learning to read' campaign.
- 7. www.pratham.org/images/resource%20working%20paper%202.pdf.

Course Code	STRESSMANAGEMENT BY YOGA	L	T	P	C			
23VSDAC02b	STRESSMANAGEMENT BY YOGA	3	0	0	3			
Semester				II				
Course Objective	es:							
1. To achiev	re overall health of body and mind							
2. To overco								
	s (CO): Student will be able to							
	nealthy mind in a healthy body thus improving social health also							
	efficiency.	1						
UNIT - I		Le	cture H	rs:				
	ht parts of yog.(Ashtanga)							
UNIT - II		Le	cture F	Irs:				
Yam and Niyam.								
UNIT - III		Le	cture H	rs:				
Do's and Don'ts is	n life.							
•	stheya, bramhacharyaand aparigraha							
	sh, tapa, swadhyay, ishwarpranidhan							
UNIT - IV		Le	cture H	rs:				
Asan and Pranaya	m							
UNIT - V		Le	cture H	rs:				
i)Variousyogposes	sand theirbenefitsformind &body							
ii)Regularizationo	ofbreathingtechniques and its effects-Types ofpranayam							
Suggested Reading	ng:							
1.'Yogic Asanas f	forGroupTarining-Part-I": Janardan SwamiYogabhyasiMandal, Na	gpur	_					
2."Rajayogaor con	nquering the Internal Nature" by Swami Vivekananda, Advaita							
Ashrama (Publica	Ashrama (Publication Department), Kolkata .							

			1	1				
Course Code	PERSONALITY DEVELOPMENT THROUGHLIFE	L	T	P	C			
23VSDAC02c	ENLIGHTENMENTSKILLS	3	0	0	3			
Semester				II				
	Course Objectives:							
	o achieve the highest goal happily							
	ne a person with stable mind, pleasing personality and determination	n						
	n wisdom in students							
	s (CO): Student will be able to							
•	d-Bhagwad-Geetawillhelpthestudentindevelopinghispersonalityand	l achiev	ve the h	ighes	t			
goal in life								
	o has studied Geetawilllead the nation and mankind to peace and pr	osperit	У					
	hatakam will help in developing versatile personality of students.							
UNIT - I		Le	cture H	rs:				
	plistic development of personality							
Verses-19,20,2								
	32(pride &heroism)							
Verses-26,28,	63,65(virtue)							
UNIT - II		Le	cture H	lrs:				
	listic development of personality							
Verses-52,53,59(c								
Verses-71,73,75,7	⁷⁸ (do's)							
UNIT - III		Le	cture H	rs:				
	to day work and duties.							
	Geeta:Chapter2-Verses41,47,48,							
*	3,21,27,35,Chapter6-Verses5,13,17,23,35,							
Chapter 18-Verses	45,46,48.	T +						
UNIT - IV		Le	cture H	rs:				
Statements of basis								
	Geeta:Chapter2-Verses 56,62,68							
	s13,14,15,16,17,18							
	lemodel. Shrimad Bhagwad Geeta:	T +						
UNIT - V		Le	cture H	rs:				
	17, Chapter 3-Verses 36, 37, 42,							
Chapter4-Verses1								
Chapter 18 – Verse								
Suggested Reading :								
	1. "SrimadBhagavadGita" by SwamiSwarupananda Advaita Ashram (Publication Department), Kolkata							
2.Bhartrihari's Three Satakam (Niti-sringar-vairagya) by P.Gopinath, Rashtriya Sanskrit Sansthanam, Delhi.								